

Application No.: 10/802,549

7

Docket No.: 524322000600

REMARKS

In a non-final Office Action mailed on September 12, 2005, claims 1-9 and 12-15 were rejected and claims 10 and 11 were objected to. By this Amendment, claims 5 and 14 have been amended to correct minor typographical errors. Claims 16-20 have been canceled in response to an earlier restriction requirement. New claims 21-25 have been added. Thus, claims 1-15 and 21-25 are pending. Applicant requests reconsideration of these pending claims.

I. Claims 1 and 12

Claim 1 was rejected under 35 U.S.C. 102(b) as being anticipated by U.S. Patent No. 5,933,351 (the Balamurugan reference). Claim 12 was rejected under 35 U.S.C. 103(a) as being unpatentable over the Balamurugan reference.

Claims 1 and 12 recite, in part, "obtaining a die placement of dice to be formed on the wafer." (Emphasis added.) Claims 1 and 12 also recite "adjusting the die placement." Note that the die placement recited as being adjusted in claims 1 and 12 are of "dice to be formed on the wafer."

The Balamurugan reference discloses a process of moving dies/dice from a wafer table to a lead frame after the dice/dies have been cut from a wafer. In particular, in column 1, lines 44-47, the Balamurugan reference discloses that the "general object of the present invention [is] to provide a system and method for locating [dice] cut from a silicon wafer on a wafer table that substantially eliminates or reduces the problems associated with locating [dice]." (Emphasis added.) Column 2, lines 28-32 discloses, "[D]ata processing system 12...controls wafer table 14 and robot assembly 16 to remove dies cut from a silicon wafer 54 on wafer table 50." (Emphasis added.) Thus, the "placement of dies" depicted in FIG. 2 and referred to in column 3, line 67 is of dies/dice that have already been formed on the wafer and cut from the wafer.

Thus, Applicant asserts that claims 1 and 12 are allowable because the Balamurugan reference fails to disclose or suggest obtaining and adjusting a die placement of dice to be formed on the wafer.

sf-2003556

Application No.: 10/802,549

8

Docket No.: 524322000600

II. Claims 2-9 and 13-15

Claims 2-9 and 13-15 variously depend from independent claims 1 and 12. Applicant asserts that these claims are allowable for at least the reason that they depend from allowable independent claims.

III. 21-25

New independent claim 21 recites, in part, "obtaining a die placement of dice to be formed on the wafer" and "adjusting the die placement." Thus, Applicant asserts that new claim 21 is allowable over the Balamurugan reference for at least the same reasons as set forth above with regard to claims 1 and 12.

Claims 22-25 variously depend from independent claim 21. Thus, Applicant asserts that these claims are allowable for at least the reason that they depend from an allowable independent claim.

sf-2003556

Application No.: 10/802,549

9

Docket No.: 524322000600

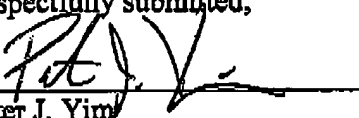
IV. Conclusion

In view of the above, each of the presently pending claims in this application is believed to be in immediate condition for allowance. Accordingly, the Examiner is respectfully requested to withdraw the outstanding rejection of the claims and to pass this application to issue. If it is determined that a telephone conference would expedite the prosecution of this application, the Examiner is invited to telephone the undersigned at the number given below.

In the event that the U.S. Patent and Trademark office determines that an extension and/or other relief is required, Applicant petitions for any required relief including extensions of time and authorizes the Commissioner to charge the cost of such petitions and/or other fees due in connection with the filing of this document to Deposit Account No. 03-1952 referencing docket no. 524322000600. However, the Commissioner is not authorized to charge the cost of the issue fee to the Deposit Account.

Dated: December 12, 2005

Respectfully submitted,

By 
Peter J. Yim

Registration No.: 44,417
MORRISON & FOERSTER LLP
425 Market Street
San Francisco, California 94105-2482
(415) 268-6373
(415) 268-7522 (fax)

sf-2003536